

Features

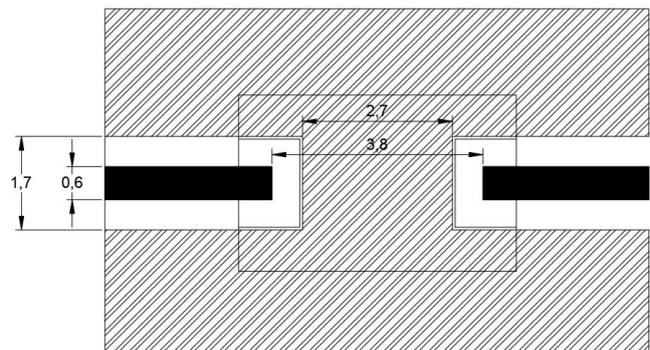
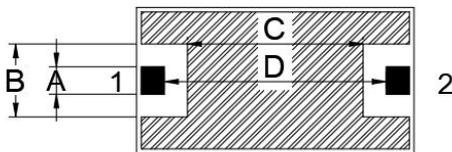
- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

NO.	Parameter	SPC
1	Frequency range(MHz)	1300~1950
2	Insertion Loss (dB)@25°C	≤1.5
3	VSWR	≤1.5
4	In Band Flatness	≤1.0
5	In/Output Impedance (Ω)	50
6	Attenuation	≥50 dB@2600~7800MHz
7	Power(W)	6W
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C		
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity		

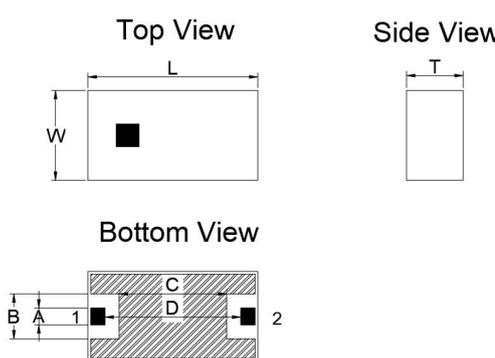
Mounting Considerations

Construction

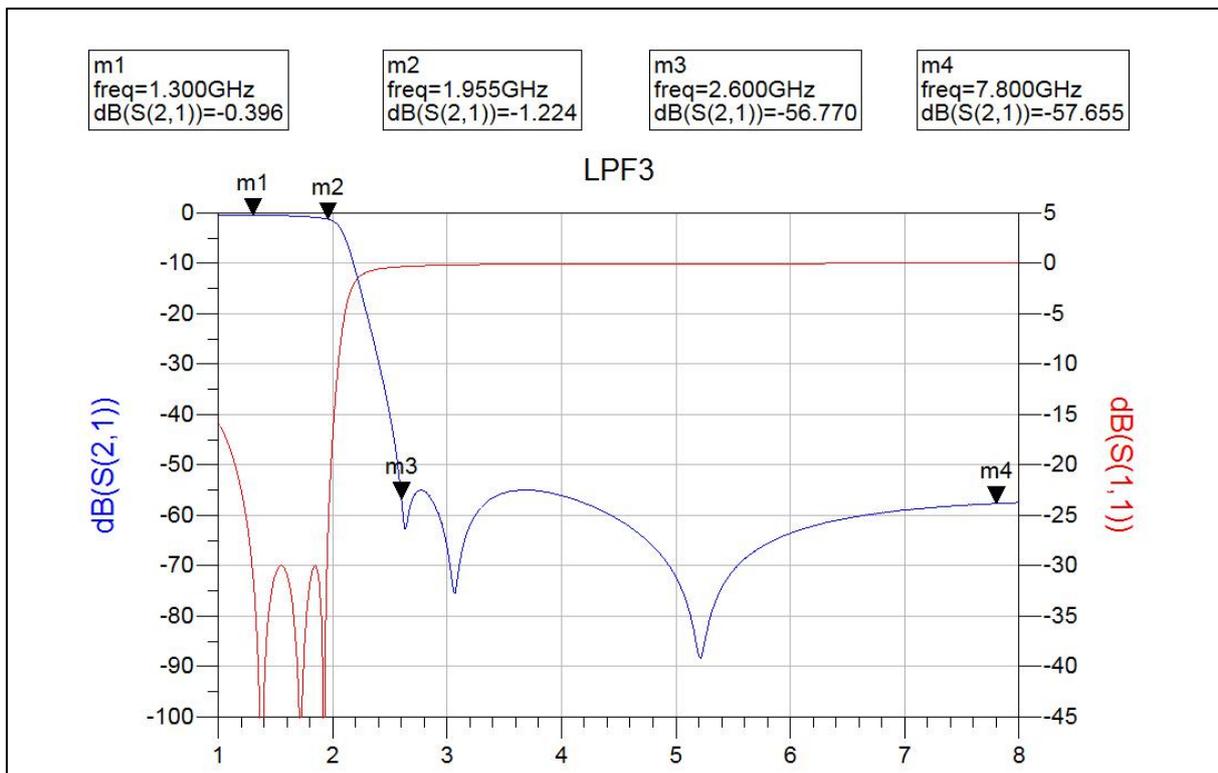


PIN	Connection	PIN	Connection
1	input Port	2	output Port

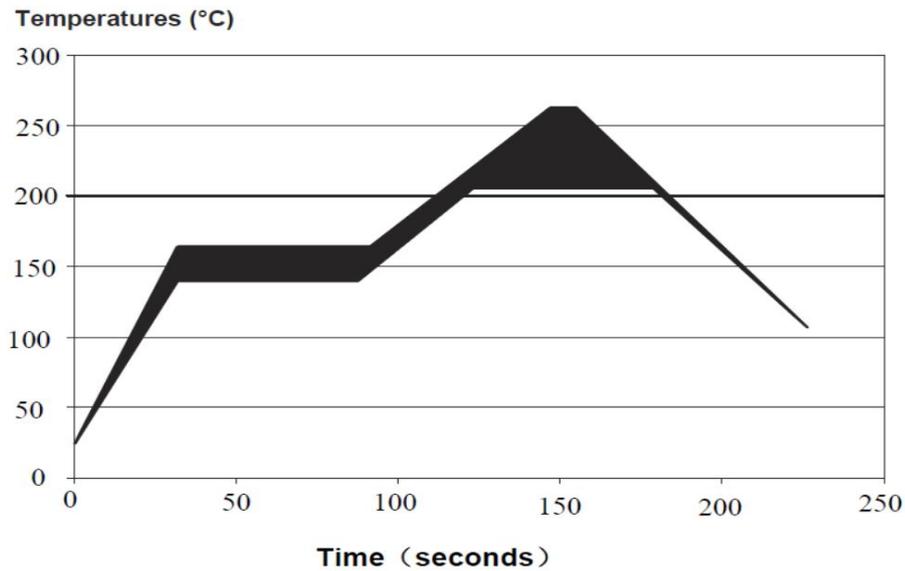
Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.15
	B	1.60 ± 0.15
	C	2.80 ± 0.15
	D	3.80 ± 0.15

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.